

# CD74HC137, CD74HCT137, CD54HC237, CD74HC237, CD74HCT237

## High-Speed CMOS Logic, 3- to 8-Line Decoder/Demultiplexer with Address Latches

### Features

- **Select One of Eight Data Outputs**
  - Active Low for CD74HC137 and CD74HCT137
  - Active High for 'HC237 and CD74HCT237
- **I/O Port or Memory Selector**
- **Two Enable Inputs to Simplify Cascading**
- **Typical Propagation Delay of 13ns at  $V_{CC} = 5V$ , 15pF,  $T_A = 25^\circ C$  (CD74HC237)**
- **Fanout (Over Temperature Range)**
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- **Wide Operating Temperature Range . . .  $-55^\circ C$  to  $125^\circ C$**
- **Balanced Propagation Delay and Transition Times**
- **Significant Power Reduction Compared to LSTTL Logic ICs**
- **HC Types**
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$ , of  $V_{CC}$  at  $V_{CC} = 5V$
- **HCT Types**
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The CD74HC137, CD74HCT137, 'HC237, and CD74HCT237 are high speed silicon gate CMOS decoders well suited to memory address decoding or data routing applications. Both circuits feature low power consumption usually associated with CMOS circuitry, yet have speeds comparable to low power Schottky TTL logic.

Both circuits have three binary select inputs ( $A_0$ ,  $A_1$  and  $A_2$ ) that can be latched by an active High Latch Enable (LE) signal to isolate the outputs from select-input changes. A "Low" LE makes the output transparent to the input and the circuit functions as a one-of-eight decoder. Two Output Enable inputs ( $\overline{OE}_1$  and  $OE_0$ ) are provided to simplify cascading and to facilitate demultiplexing. The demultiplexing function is accomplished by using the  $A_0$ ,  $A_1$ ,  $A_2$  inputs to select the desired output and using one of the other Output Enable inputs as the data input while holding the other Output Enable input in its active state. In the CD74HC137 and CD74HCT137 the selected output is a "Low"; in the 'HC237 and CD74HCT237 the selected output is a "High".

### Ordering Information

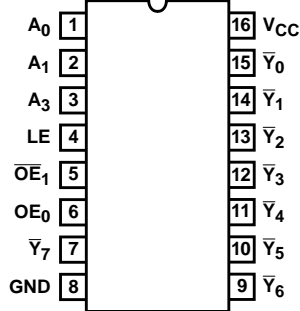
PART NUMBER	TEMP. RANGE ( $^\circ C$ )	PACKAGE
CD54HC237F3A	-55 to 125	16 Ld CERDIP
CD74HC137E	-55 to 125	16 Ld PDIP
CD74HC137PW	-55 to 125	16 Ld TSSOP
CD74HC137PWR	-55 to 125	16 Ld TSSOP
CD74HC137PWT	-55 to 125	16 Ld TSSOP
CD74HC237E	-55 to 125	16 Ld PDIP
CD74HC237M	-55 to 125	16 Ld SOIC
CD74HC237MT	-55 to 125	16 Ld SOIC
CD74HC237M96	-55 to 125	16 Ld SOIC
CD74HC237NSR	-55 to 125	16 Ld SOP
CD74HC237PW	-55 to 125	16 Ld TSSOP
CD74HC237PWR	-55 to 125	16 Ld TSSOP
CD74HC237PWT	-55 to 125	16 Ld TSSOP
CD74HCT137E	-55 to 125	16 Ld PDIP
CD74HCT137MT	-55 to 125	16 Ld SOIC
CD74HCT137M96	-55 to 125	16 Ld SOIC
CD74HCT237E	-55 to 125	16 Ld PDIP

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

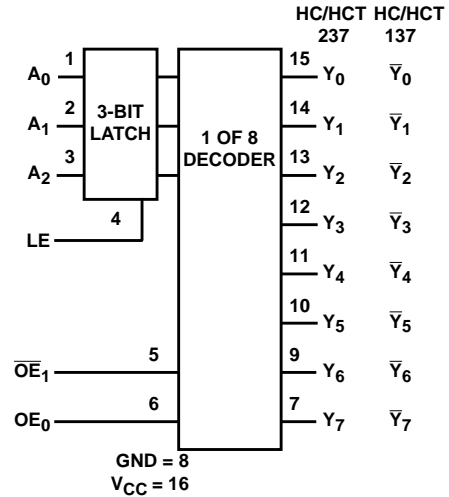
# CD74HC137, CD74HCT137, CD54HC237, CD74HC237, CD74HCT237

## Pinout

CD54HC237 (CERDIP)  
 CD74HC137 (PDIP, TSSOP)  
 CD74HCT137 (PDIP, SOIC)  
 CD74HC237 (PDIP, SOIC, SOP, TSSOP)  
 CD74HCT237 (PDIP)  
 TOP VIEW



## Functional Diagram



'HC137, 'HCT137 TRUTH TABLE

INPUTS						OUTPUTS							
LE	OE <sub>0</sub>	OE <sub>1</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	Y <sub>0</sub>	Y <sub>1</sub>	Y <sub>2</sub>	Y <sub>3</sub>	Y <sub>4</sub>	Y <sub>5</sub>	Y <sub>6</sub>	Y <sub>7</sub>
X	X	H	X	X	X	H	H	H	H	H	H	H	H
X	L	X	X	X	X	H	H	H	H	H	H	H	H
L	H	L	L	L	L	L	H	H	H	H	H	H	H
L	H	L	L	L	H	H	L	H	H	H	H	H	H
L	H	L	L	H	L	H	H	L	H	H	H	H	H
L	H	L	L	H	H	H	H	H	L	H	H	H	H
L	H	L	H	L	L	H	H	H	H	L	H	H	H
L	H	L	H	L	H	H	H	H	H	H	L	H	H
L	H	L	H	H	L	H	H	H	H	H	H	L	H
L	H	L	H	H	H	H	H	H	H	H	H	H	L
H	H	L	X	X	X	Depends upon the address previously applied while LE was at a logic low.							

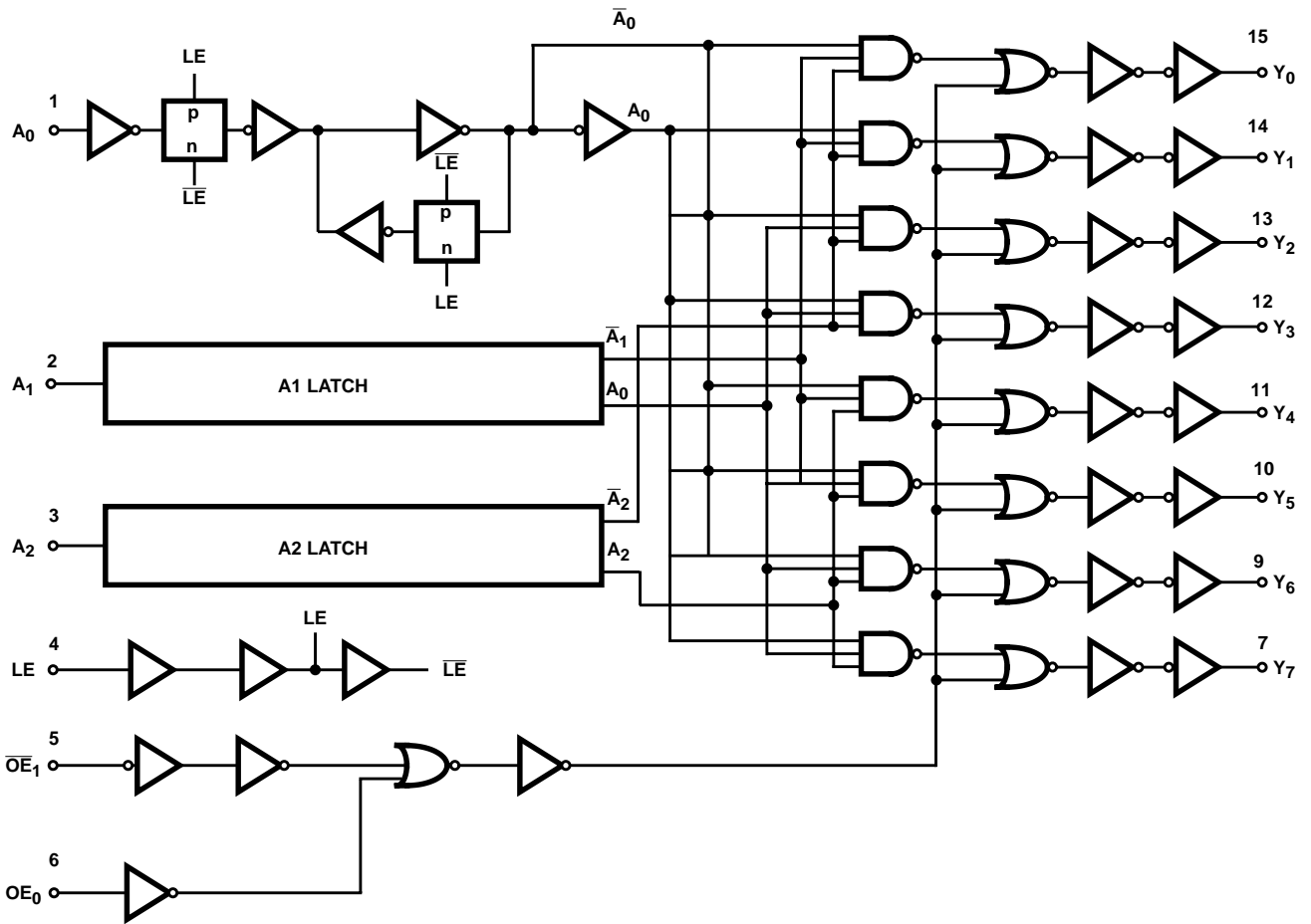
H = High Voltage Level, L = Low Voltage Level, X = Don't Care

'HC237, 'HCT237 TRUTH TABLE

INPUTS						OUTPUTS							
LE	OE <sub>0</sub>	OE <sub>1</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	Y <sub>0</sub>	Y <sub>1</sub>	Y <sub>2</sub>	Y <sub>3</sub>	Y <sub>4</sub>	Y <sub>5</sub>	Y <sub>6</sub>	Y <sub>7</sub>
X	X	H	X	X	X	L	L	L	L	L	L	L	L
X	L	X	X	X	X	L	L	L	L	L	L	L	L
L	H	L	L	L	L	H	L	L	L	L	L	L	L
L	H	L	L	L	H	L	H	L	L	L	L	L	L
L	H	L	L	H	L	L	L	H	L	L	L	L	L
L	H	L	L	H	H	L	L	L	H	L	L	L	L
L	H	L	H	L	L	L	L	L	L	H	L	L	L
L	H	L	H	L	H	L	L	L	L	L	H	L	L
L	H	L	H	H	L	L	L	L	L	L	L	H	L
L	H	L	H	H	H	L	L	L	L	L	L	L	H
H	H	L	X	X	X	Depends upon the address previously applied while LE was at a logic low.							

H = High Voltage Level, L = Low Voltage Level, X = Don't Care

**Functional Block Diagram**



# CD74HC137, CD74HCT137, CD54HC237, CD74HC237, CD74HCT237

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 7V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ .....	$\pm 50mA$

## Thermal Information

Package Thermal Impedance, $\theta_{JA}$ (see Note 1):	
E (PDIP) Package .....	67°C/W
M (SOIC) Package .....	73°C/W
NS (SOP) Package .....	64°C/W
PW (TSSOP) Package .....	108°C/W
Maximum Junction Temperature .....	150°C
Maximum Storage Temperature Range .....	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s) .....	300°C
(SOIC - Lead Tips Only)	

## Operating Conditions

Temperature Range ( $T_A$ ) .....	-55°C to 125°C
Supply Voltage Range, $V_{CC}$	
HC Types .....	.2V to 6V
HCT Types .....	4.5V to 5.5V
DC Input or Output Voltage, $V_I, V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Time	
2V .....	1000ns (Max)
4.5V .....	500ns (Max)
6V .....	400ns (Max)

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

### NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		$V_I$ (V)	$I_O$ (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>												
High Level Input Voltage	$V_{IH}$	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	$V_{IL}$	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-	-	-	-	-	-	-	-	-	V
			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	-	-	-	-	-	-	-	-	-	V
			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	$I_I$	$V_{CC}$ or GND	-	6	-	-	$\pm 0.1$	-	$\pm 1$	-	$\pm 1$	$\mu A$

**CD74HC137, CD74HCT137, CD54HC237, CD74HC237, CD74HCT237**

**DC Electrical Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	6	-	-	8	-	80	-	160	μA
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> and GND	0	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub> (Note 2)	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE:

2. For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

**HCT Input Loading Table**

INPUT	UNIT LOADS
All	1.5

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Table, e.g., 360μA max at 25°C.

**Prerequisite For Switching Specifications**

PARAMETER	SYMBOL	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>										
A <sub>n</sub> to LE Setup Time	t <sub>SU</sub>	2	50	-	-	65	-	75	-	ns
		4.5	10	-	-	13	-	15	-	ns
		6	9	-	-	11	-	13	-	ns
A <sub>n</sub> to LE Hold Time	t <sub>H</sub>	2	30	-	-	40	-	45	-	ns
		4.5	6	-	-	8	-	9	-	ns
		6	5	-	-	7	-	8	-	ns

**CD74HC137, CD74HCT137, CD54HC237, CD74HC237, CD74HCT237**

**Prerequisite For Switching Specifications (Continued)**

PARAMETER	SYMBOL	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
LE Pulse Width	t <sub>W</sub>	2	50	-	-	65	-	75	-	ns
		4.5	10	-	-	13	-	15	-	ns
		6	9	-	-	1	-	13	-	ns
<b>HCT TYPES</b>										
An to LE Setup Time	t <sub>SU</sub>	4.5	10	-	-	13	-	15	-	ns
An to LE Hold Time	t <sub>H</sub>	4.5	7	-	-	9	-	11	-	ns
		CD74HCT237	t <sub>H</sub>	4.5	5	-	-	5	-	5
LE Pulse Width	t <sub>W</sub>	4.5	10	-	-	13	-	15	-	ns

**Switching Specifications** Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>											
Propagation Delay CD74HC137, CD74HCT137 An to any $\bar{Y}$	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	180	-	225	-	270	ns
			4.5	-	-	36	-	45	-	54	ns
			6	-	-	31	-	38	-	46	ns
Propagation Delay 'HC237, CD74HCT237 An to any Y	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	160	-	200	-	240	ns
			4.5	-	-	32	-	40	-	48	ns
			6	-	-	27	-	34	-	41	ns
Address to Output CD74HC137	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 15pF	5	5	15	-	-	-	-	ns	
'HC237	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 15pF	5	-	13	-	-	-	-	ns	
OE <sub>0</sub> to any $\bar{Y}$ or Y	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	145	-	180	-	220	ns
			4.5	-	-	29	-	36	-	44	ns
			6	-	-	25	-	31	-	38	ns
OE <sub>1</sub> to any $\bar{Y}$ or Y	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	-	145	-	180	-	220	ns
			4.5	-	-	29	-	36	-	44	ns
			6	-	-	25	-	31	-	38	ns
LE to any $\bar{Y}$ or Y	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	-	190	-	240	-	285	ns
			4.5	-	-	38	-	48	-	57	ns
			6	-	-	32	-	41	-	48	ns
Power Dissipation Capacitance, (Notes 3, 4) CD74HC137	C <sub>PD</sub>	C <sub>L</sub> = 15pF	5	-	19	-	-	-	-	-	pF
			'HC237	C <sub>PD</sub>	C <sub>L</sub> = 15pF	5	-	23	-	-	-
Output Transition Time	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	C <sub>I</sub>	-	-	-	-	-	-	-	-	10	pF

# CD74HC137, CD74HCT137, CD54HC237, CD74HC237, CD74HCT237

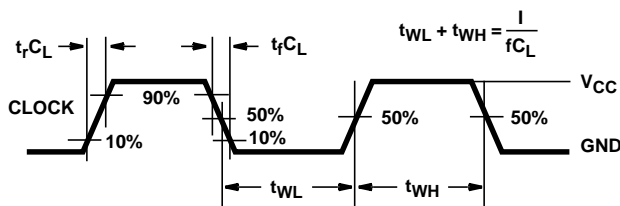
## Switching Specifications Input $t_r, t_f = 6\text{ns}$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HCT TYPES</b>											
Propagation Delay An to any $\bar{Y}$ or Y Address to Output	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	38	-	48	-	57	ns
	$t_{PLH}, t_{PHL}$	$C_L = 15\text{pF}$	5	-	16	-	-	-	-	-	ns
$OE_0$ to any Y (HC137)	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	35	-	44	-	53	ns
$OE_0$ to any $\bar{Y}$ (HC237)	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	33	-	41	-	60	ns
$\overline{OE}_1$ to any $\bar{Y}$ (HC137)	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	4.5	-	-	37	-	46	-	56	ns
$\overline{OE}_1$ to any $\bar{Y}$ (HC237)	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	4.5	-	-	35	-	44	-	53	ns
LE to any Y (HC137)	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	4.5	-	-	44	-	55	-	66	ns
LE to any $\bar{Y}$ (HC237)	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	4.5	-	-	42	-	53	-	63	ns
Power Dissipation Capacitance, (Notes 3, 4) CD74HC137	$C_{PD}$	$C_L = 15\text{pF}$	5	-	19	-	-	-	-	-	pF
			'HC237	5	-	23	-	-	-	-	-
Output Transition Time	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	4.5	-	-	15	-	19	-	22	ns
Input Capacitance	$C_i$	-	-	-	-	10	-	10	-	10	pF

**NOTES:**

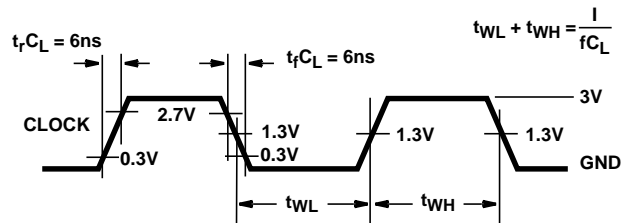
- $C_{PD}$  is used to determine the dynamic power consumption, per gate.
- $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where:  $f_i$  = Input Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

## Test Circuits and Waveforms



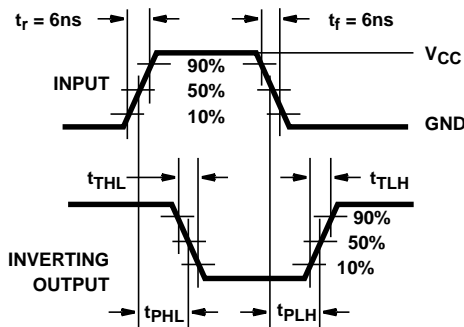
NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

**FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH**

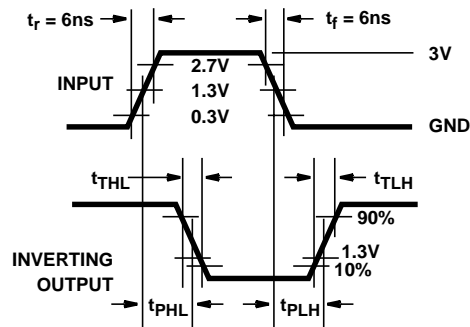


NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

**FIGURE 2. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH**



**FIGURE 3. HC AND HCU TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**



**FIGURE 4. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**

Test Circuits and Waveforms (Continued)

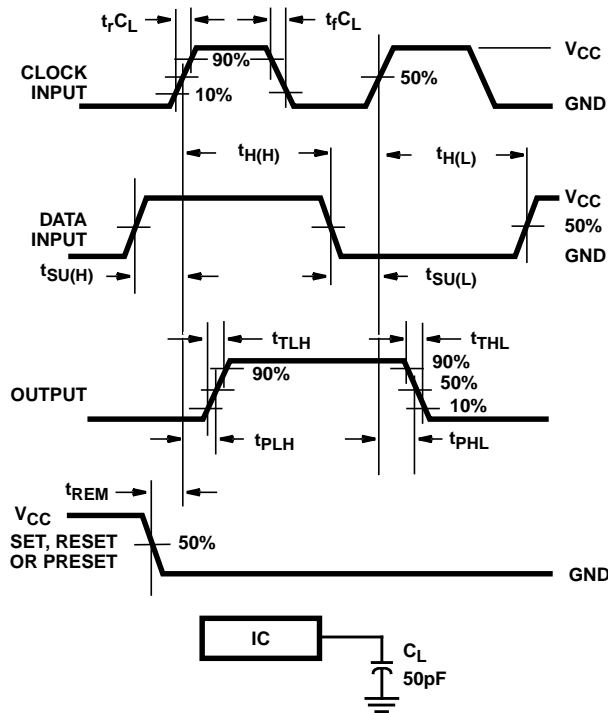


FIGURE 5. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

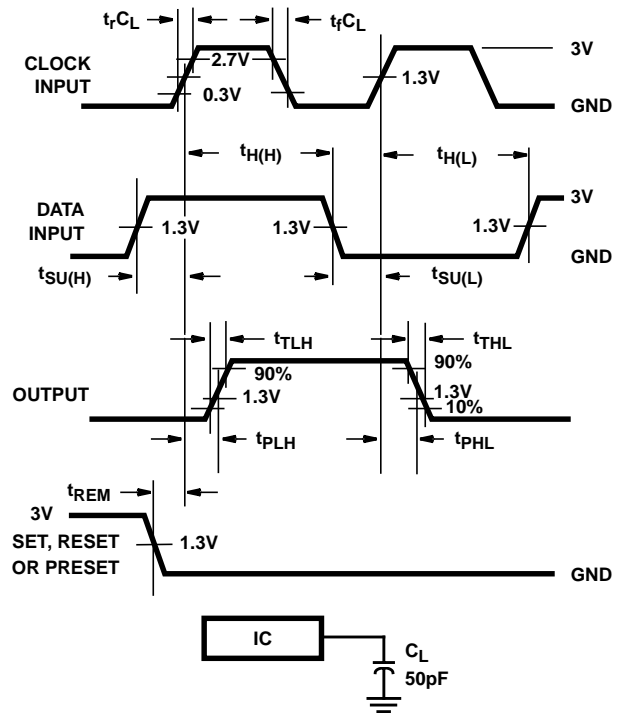


FIGURE 6. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8860601EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8860601EA CD54HC237F3A	<a href="#">Samples</a>
CD54HC237F	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54HC237F	<a href="#">Samples</a>
CD54HC237F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8860601EA CD54HC237F3A	<a href="#">Samples</a>
CD74HC137E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC137E	<a href="#">Samples</a>
CD74HC137PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ137	<a href="#">Samples</a>
CD74HC137PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ137	<a href="#">Samples</a>
CD74HC237E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC237E	<a href="#">Samples</a>
CD74HC237EE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC237E	<a href="#">Samples</a>
CD74HC237M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC237M	<a href="#">Samples</a>
CD74HC237M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-55 to 125	HC237M	<a href="#">Samples</a>
CD74HC237M96G4	ACTIVE	SOIC	D	16	2500	TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC237ME4	ACTIVE	SOIC	D	16	40	TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>
CD74HC237NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC237M	<a href="#">Samples</a>
CD74HC237PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-55 to 125	HJ237	<a href="#">Samples</a>
CD74HC237PWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ237	<a href="#">Samples</a>
CD74HCT137E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT137E	<a href="#">Samples</a>
CD74HCT137M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT137M	<a href="#">Samples</a>
CD74HCT137MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT137M	<a href="#">Samples</a>
CD74HCT137MTE4	ACTIVE	SOIC	D	16	250	TBD	Call TI	Call TI	-55 to 125		<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HCT237E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT237E	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF CD54HC237, CD74HC237 :**

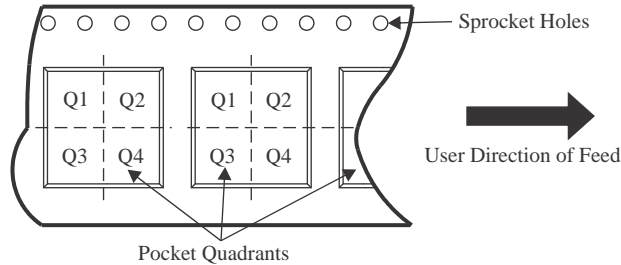
- Catalog : [CD74HC237](#)

- Military : [CD54HC237](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


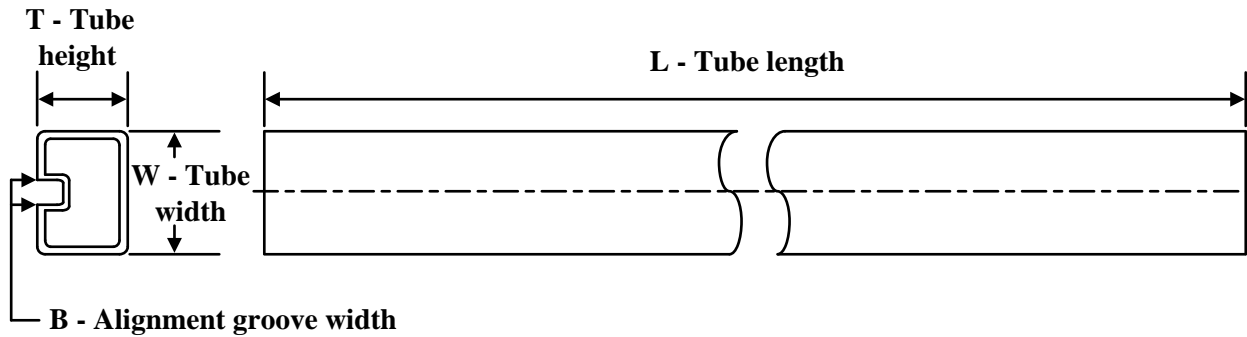
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC137PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC237M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC237M96	SOIC	D	16	2500	330.0	16.4	6.6	9.3	2.1	8.0	16.0	Q1
CD74HC237NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC237PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC237PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC237PWR	TSSOP	PW	16	2000	330.0	12.4	6.85	5.45	1.6	8.0	12.0	Q1
CD74HC237PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HCT137M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC137PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC237M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74HC237M96	SOIC	D	16	2500	366.0	364.0	50.0
CD74HC237NSR	SO	NS	16	2000	356.0	356.0	35.0
CD74HC237PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC237PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC237PWR	TSSOP	PW	16	2000	366.0	364.0	50.0
CD74HC237PWT	TSSOP	PW	16	250	356.0	356.0	35.0
CD74HCT137M96	SOIC	D	16	2500	340.5	336.1	32.0

**TUBE**




\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74HC137E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC137E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC137PW	PW	TSSOP	16	90	530	10.2	3600	3.5
CD74HC237E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC237E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC237EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC237EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC237M	D	SOIC	16	40	507	8	3940	4.32
CD74HCT137E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT137E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT237E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT237E	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



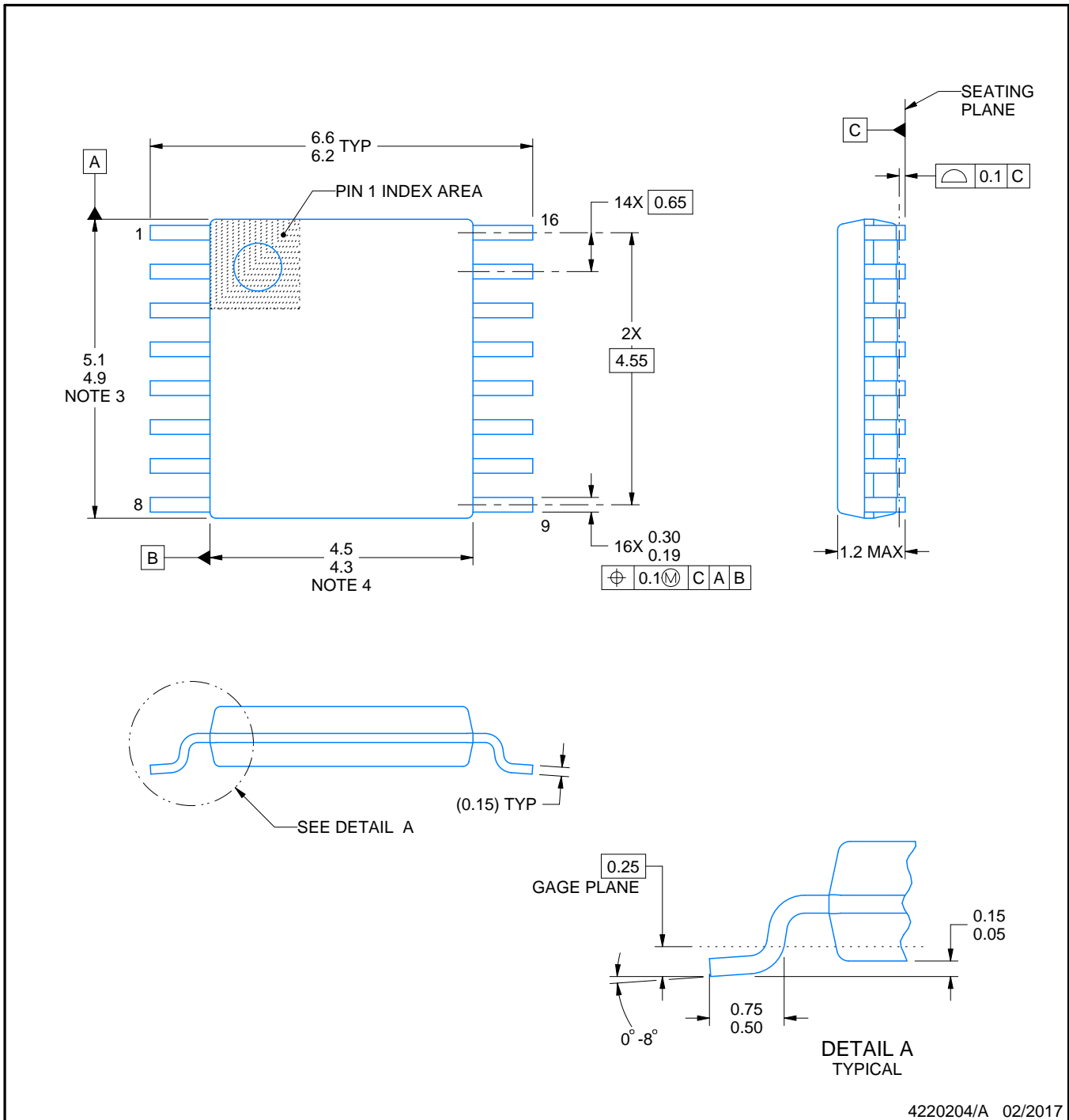
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



4220204/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

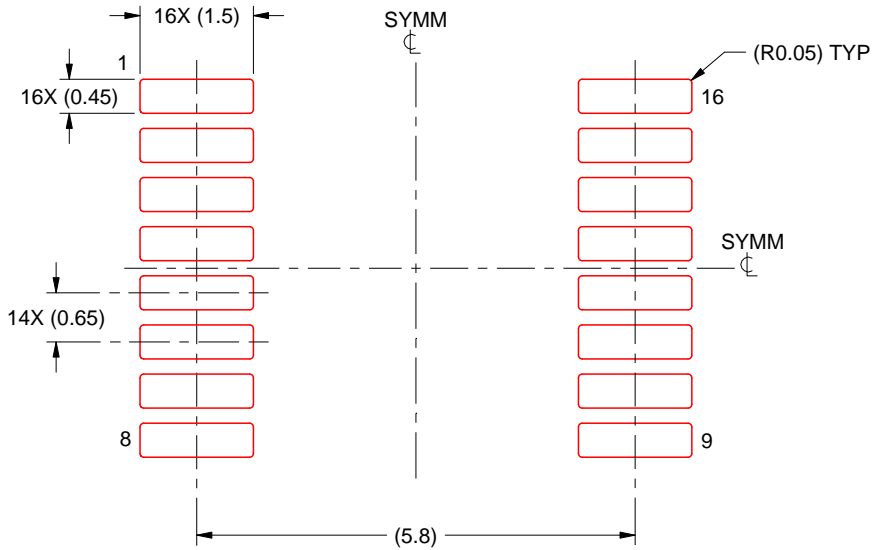
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

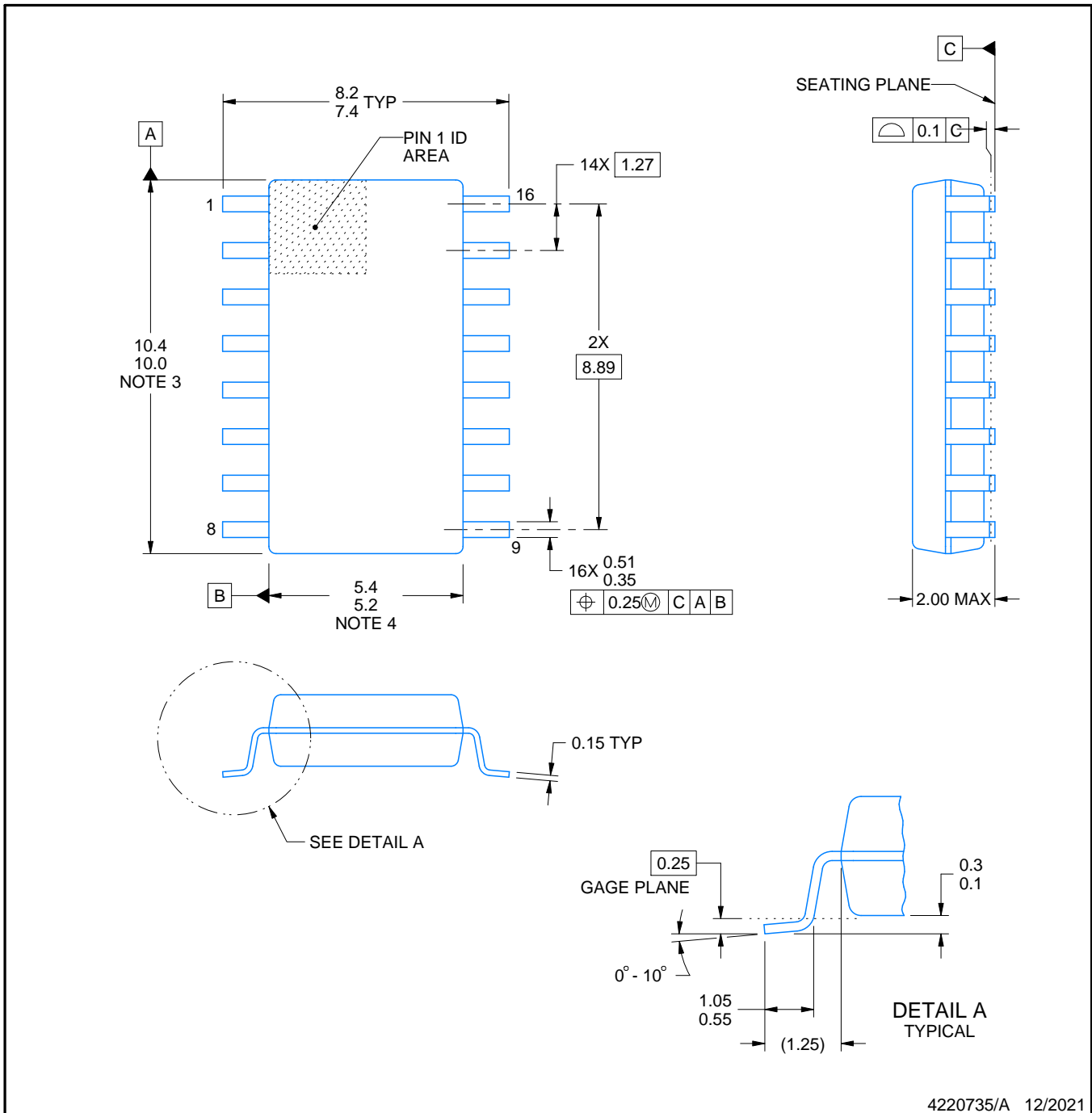


# PACKAGE OUTLINE

## NS0016A

### SOP - 2.00 mm max height

SOP



4220735/A 12/2021

#### NOTES:

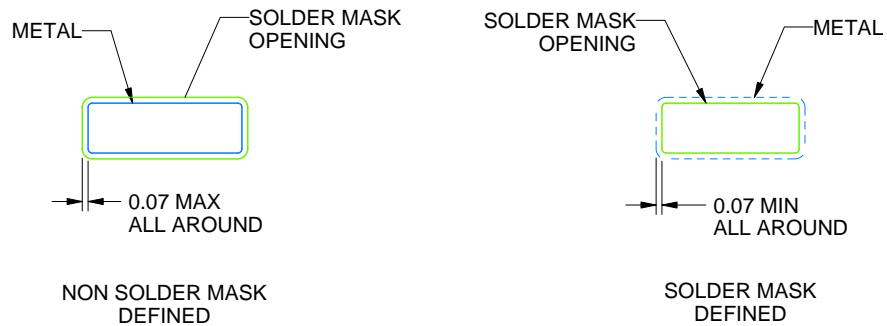
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

# EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

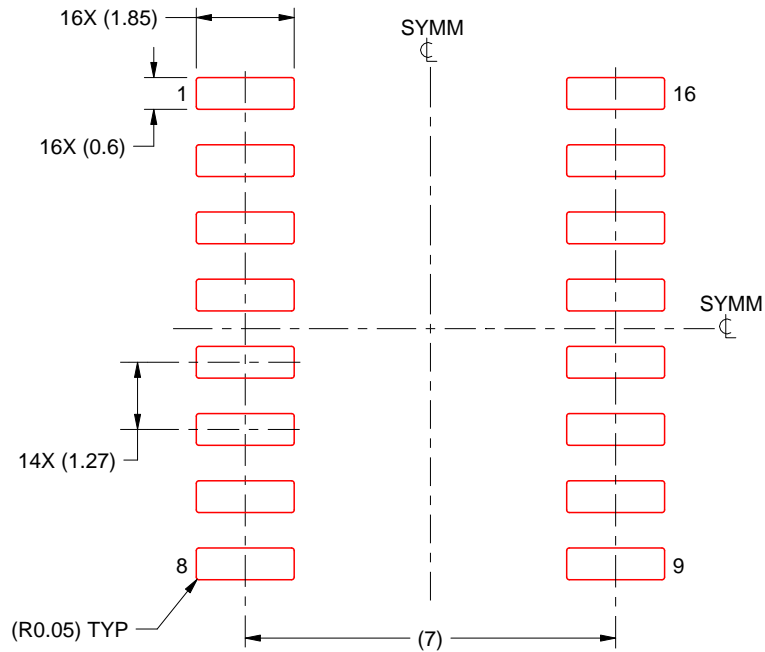
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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